

MEG-00-007



October 26, 2001

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To: Commissioner of Patents and Trademarks  
Washington, D.C. 20231

Fr: George O. Saile, Reg. No. 19,572  
20 McIntosh Drive  
Poughkeepsie, N.Y. 12603

RECEIVED  
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TO 2830 MAIL ROOM

Subject:

Serial No. 09/945,436 09/04/01

Jin-Yuan Lee, Mou-Shiung Lin

A METHOD FOR MAKING HIGH-  
PERFORMANCE RF INTEGRATED CIRCUITS

Grp. Art Unit: 2832

#### INFORMATION DISCLOSURE STATEMENT

Enclosed is Form PTO-1449, Information Disclosure Citation  
In An Application.

The following Patents and/or Publications are submitted to  
comply with the duty of disclosure under CFR 1.97-1.99 and  
37 CFR 1.56. Copies of each document is included herewith.

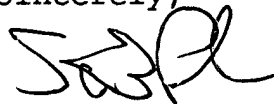
U.S. Patent 6,046,101 to Dass et al., "Passivation  
Technology Combining Improved Adhesion in Passivation and a  
Scribe Street Without Passivation", discloses a process where  
passivation is not formed over some scribe streets.

U.S. Patent 5,904,546 to Wood et al., "Method and Apparatus for Dicing Semiconductor Wafers," discloses a dicing process on scribe lines to form planar inductors.

U.S. Patent 6,043,109 to Yang et al., "Method of Fabricating Wafer-Level Package," discloses a IC process (including inductors) where wafers are sawed on scribe lines.

U.S. Patent 5,387,551 to Mizoguchi et al., "Method of Manufacturing Flat Inductance Element," discloses an inductor process and dicing process.

Sincerely,

A handwritten signature in black ink, appearing to read 'SBA', is written over the typed name.

Stephen B. Ackerman,  
Reg. No. 37761